

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.06629	100.0	1
			<b>Subtotal</b>	<b>0.06629</b>	<b>100</b>	<b>1</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.15114	100.0	2.28
			<b>Subtotal</b>	<b>0.15114</b>	<b>100</b>	<b>2.28</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00974	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00649	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00974	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03571	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.40576	99.81	488.8594
			<b>Subtotal</b>	<b>32.46744</b>	<b>100</b>	<b>489.79001</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.34251	100.0	5.167
			<b>Subtotal</b>	<b>0.34251</b>	<b>100</b>	<b>5.167</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.29481	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.60993	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.4633	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19856	0.3	2.99532
	Polymer	Epoxy resin system		6.61851	10.0	99.844
			<b>Subtotal</b>	<b>66.18511</b>	<b>100</b>	<b>998.44</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.07875	10.0	1.188
	Silver alloy	Silver (Ag)	7440-22-4	0.01575	2.0	0.2376
	Lead alloy	Lead (Pb)	7439-92-1	0.69301	88.0	10.4544
			<b>Subtotal</b>	<b>0.78751</b>	<b>100</b>	<b>11.88</b>
			<b>Total</b>	<b>100</b>	<b>100</b>	<b>1508.55701</b>

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